NTB5605PG-VB Datasheet

P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY			
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)	Q_g (Typ)
- 60	0.064 at V_{GS} = - 10 V	- 30	12
	0.077 at V_{GS} = - 4.5 V	- 28	

FEATURES

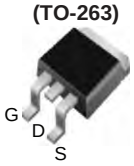
- Trench Power MOSFET 100
- % UIS Tested

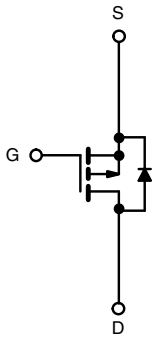
APPLICATIONS

- Load Switch

RoHS COMPLIANT
HALOGEN FREE

D²PAK
(TO-263)





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T_C = 25 °C, unless otherwise noted				
Parameter		**Symbol**	**Limit**	**Unit**
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current (T_J = 175 °C)	T_C = 25 °C	I_D	- 30	A
	T_C = 100 °C		- 20	
Pulsed Drain Current		I_{DM}	- 90	
Continuing Source Current (Diode Conduction)		I_S	- 28	
Avalanche Current		I_{AS}	- 31	
Single Pulse Avalanche Energy	L = 0.1 mH	E_{AS}	7.2	mJ
Maximum Power Dissipation	T_C = 25 °C	P_D	60 [a]	W
	T_A = 25 °C		6 [b]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		**Symbol**	**Typical**	**Maximum**	**Unit**
Junction-to-Ambient [b]	t ≤ 10 sec	R_{thJA}	20	25	°C/W
	Steady State		62	75	
Junction-to-Case		R_{thJC}	5	6	

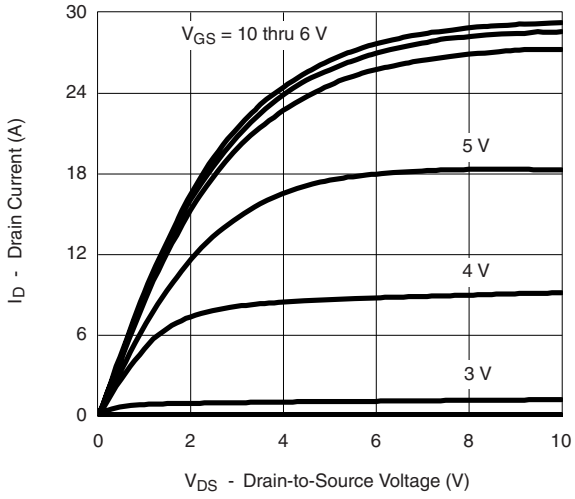
Notes:
a. See SOA curve for voltage derating.
b. Surface Mounted on 1" x 1" FR-4 boad.

SPECIFICATIONS T_J = 25 °C, unless otherwise noted						
Parameter	**Symbol**	**Test Conditions**	**Min**	**Typ[a]**	**Max**	**Unit**
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = - 250 µA	- 60			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = - 250 µA	- 1.0	- 2.0	- 3.0	
Gate-Body Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = - 60 V, V_{GS} = 0 V			- 1	µA
		V_{DS} = - 60 V, V_{GS} = 0 V, T_J = 125 °C			- 50	
		V_{DS} = - 60 V, V_{GS} = 0 V, T_J = 175 °C			- 150	
On-State Drain Current[b]	$I_{D(on)}$	V_{DS} = - 5 V, V_{GS} = - 10 V	- 10			A
Drain-Source On-State Resistance[b]	$r_{DS(on)}$	V_{GS} = - 10 V, I_D = - 5 A		0.064		Ω
		V_{GS} = - 10 V, I_D = - 5 A, T_J = 125 °C		0.110		
		V_{GS} = - 10 V, I_D = - 5 A, T_J = 175 °C		0.250		
		V_{GS} = - 4.5 V, I_D = - 2 A		0.077		
Forward Transconductance[b]	g_{fs}	V_{DS} = - 15 V, I_D = - 5 A		8		S
Dynamic						
Input Capacitance	C_{iss}	V_{DS} = - 25 V, V_{GS} = 0 V, f = 1 MHz		1000		pF
Output Capacitance	C_{oss}			210		
Reverse Transfer Capacitance	C_{rss}			110		
Total Gate Charge	Q_g	V_{DS} = - 30 V, V_{GS} = - 10 V, I_D = - 8.4 A		12.5	19	nC
Gate-Source Charge	Q_{gs}			2.3		
Gate-Drain Charge	Q_{gd}			3.2		
Gate Resistance	R_g	f = 1 MHz		8.0		Ω
Turn-On Delay Time[c]	$t_{d(on)}$	V_{DD} = - 30 V, R_L = 3.57 Ω $I_D \cong$ - 8.4 A, V_{GEN} = - 10 V, R_G = 2.5 Ω		5	10	ns
Rise Time[c]	t_r			14	25	
Turn-Off Delay Time[c]	$t_{d(off)}$			15	25	
Fall Time[c]	t_f			7	12	
Source-Drain Diode Ratings and Characteristics (T_C = 25 °C)[b]						
Pulsed Current	I_{SM}				- 30	A
Forward Voltage[b]	V_{SD}	I_F = - 2 A, V_{GS} = 0 V		- 0.9	- 1.3	V
Reverse Recovery Time	t_{rr}	I_F = - 8 A, di/dt = 100 A/µs		50	80	ns
Reverse Recovery Time	Q_{rr}			80	120	nC

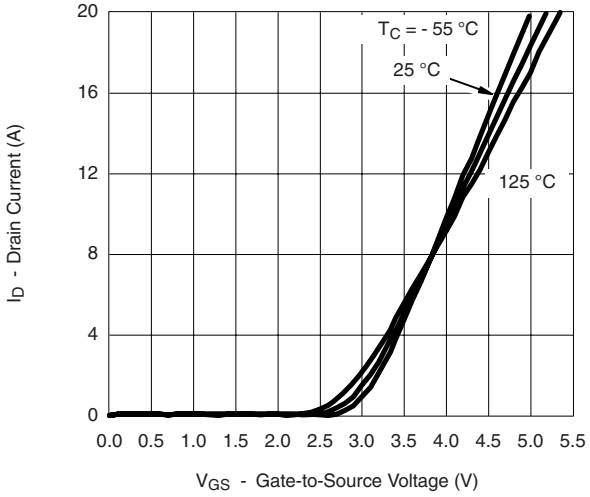
Notes:
a. Guaranteed by design, not subject to production testing.
b. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

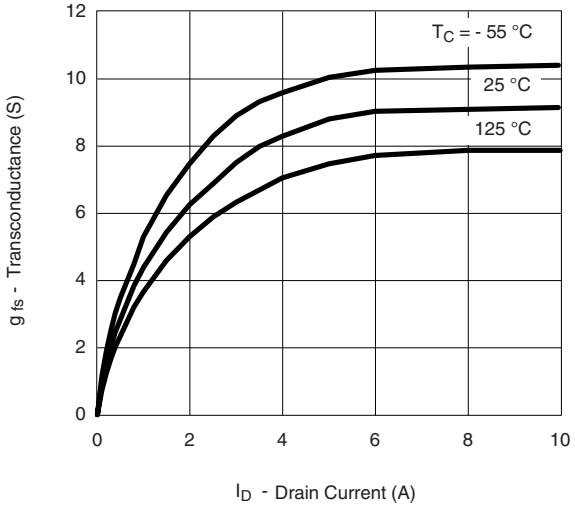
TYPICAL CHARACTERISTICS 25 °C unless noted



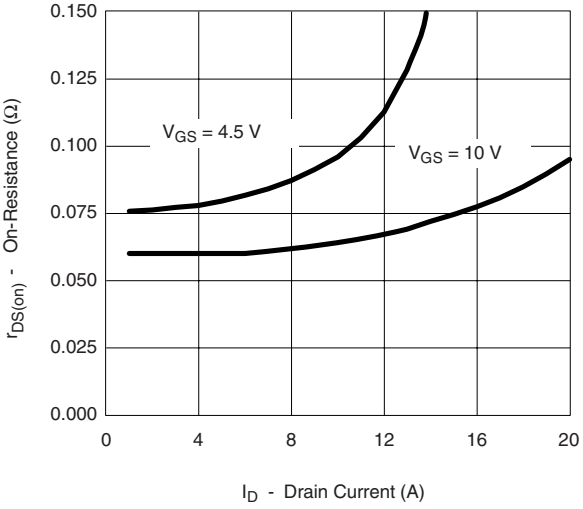
Output Characteristics



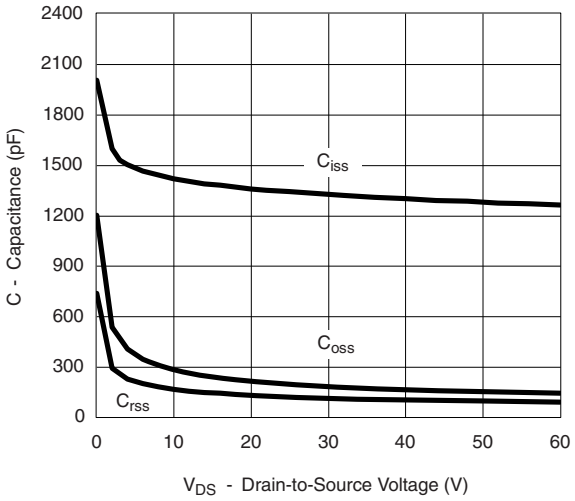
Transfer Characteristics



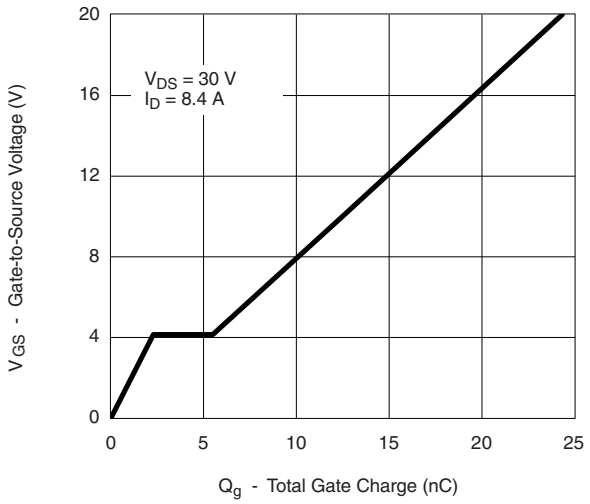
Transconductance



On-Resistance vs. Drain Current

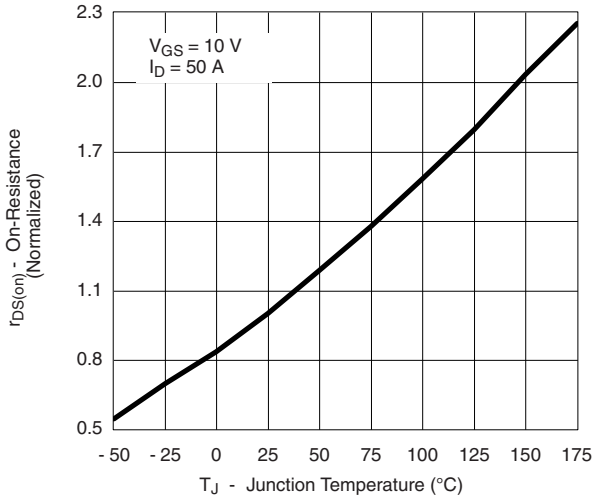


Capacitance

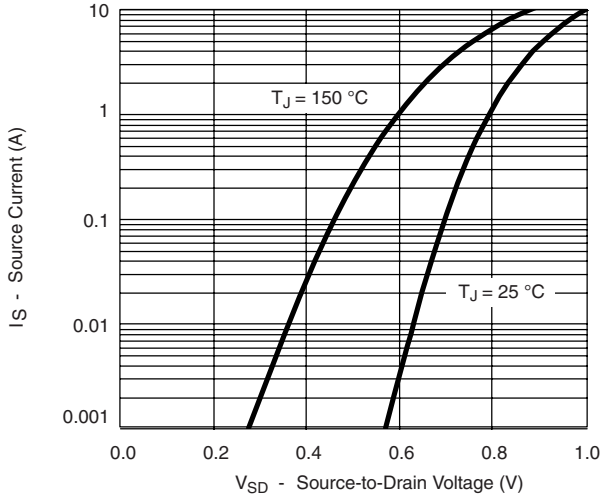


Gate Charge

TYPICAL CHARACTERISTICS 25 °C unless noted

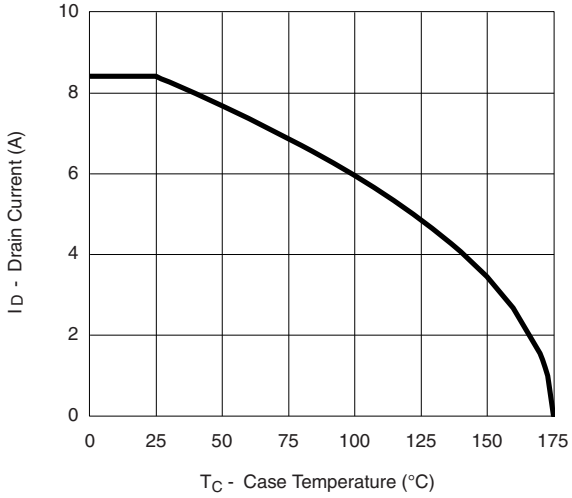


On-Resistance vs. Junction Temperature

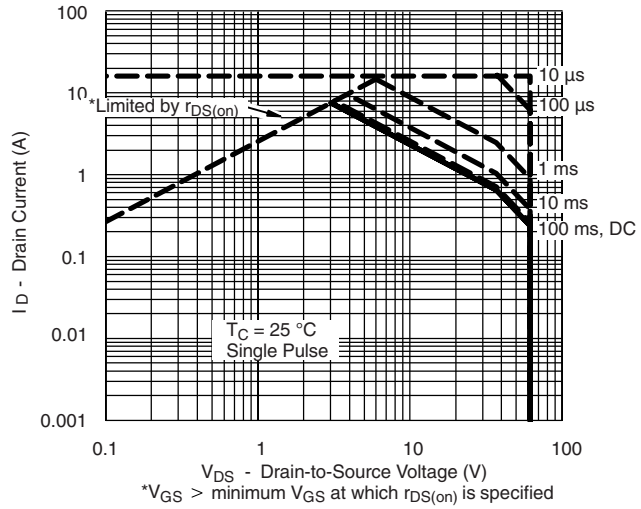


Source-Drain Diode Forward Voltage

THERMAL RATINGS

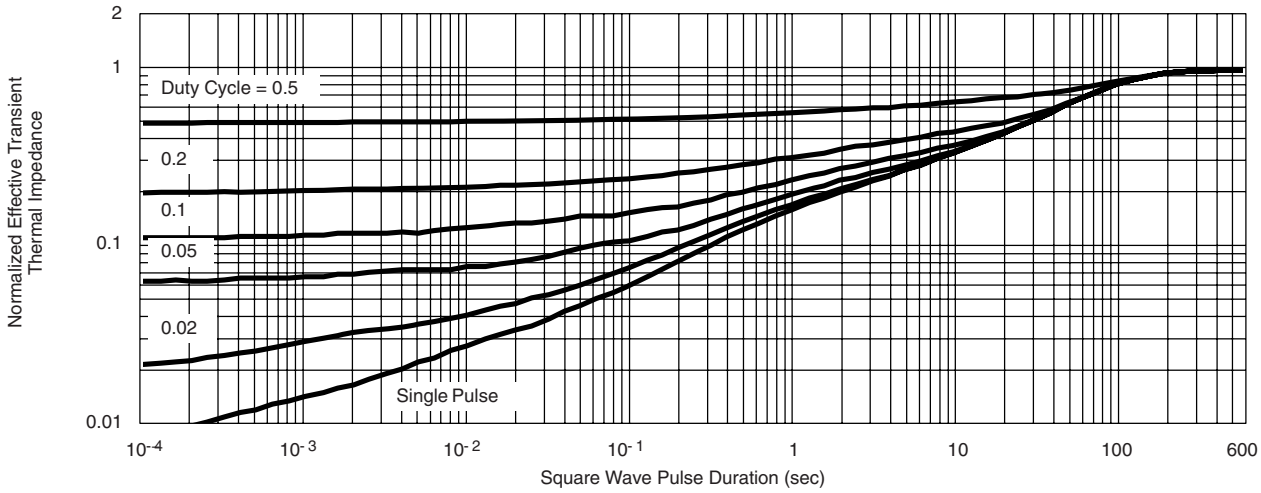


Drain Current vs. Case Temperature

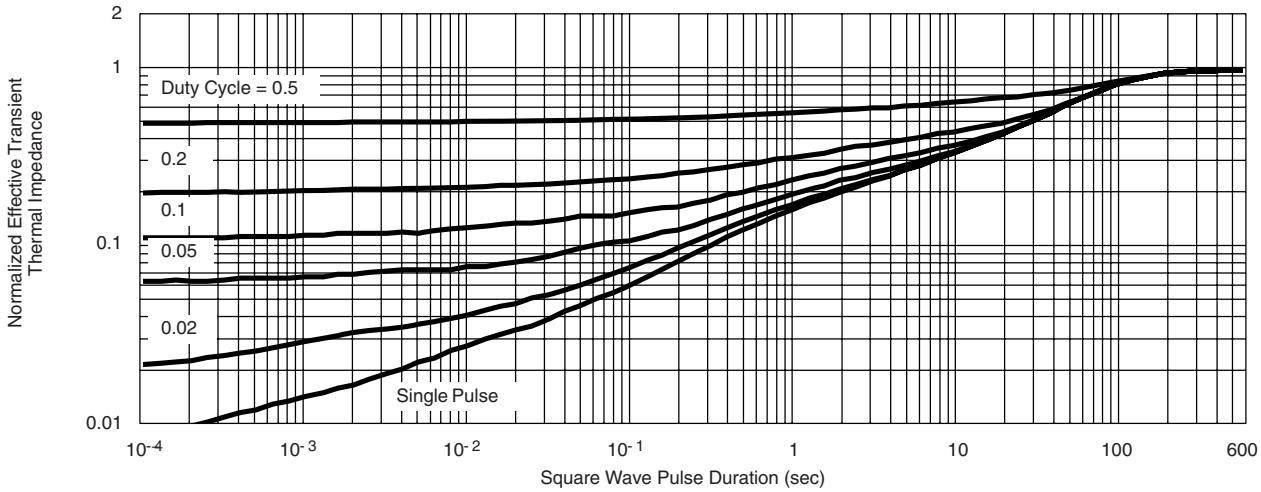


Safe Operating Area

THERMAL RATINGS

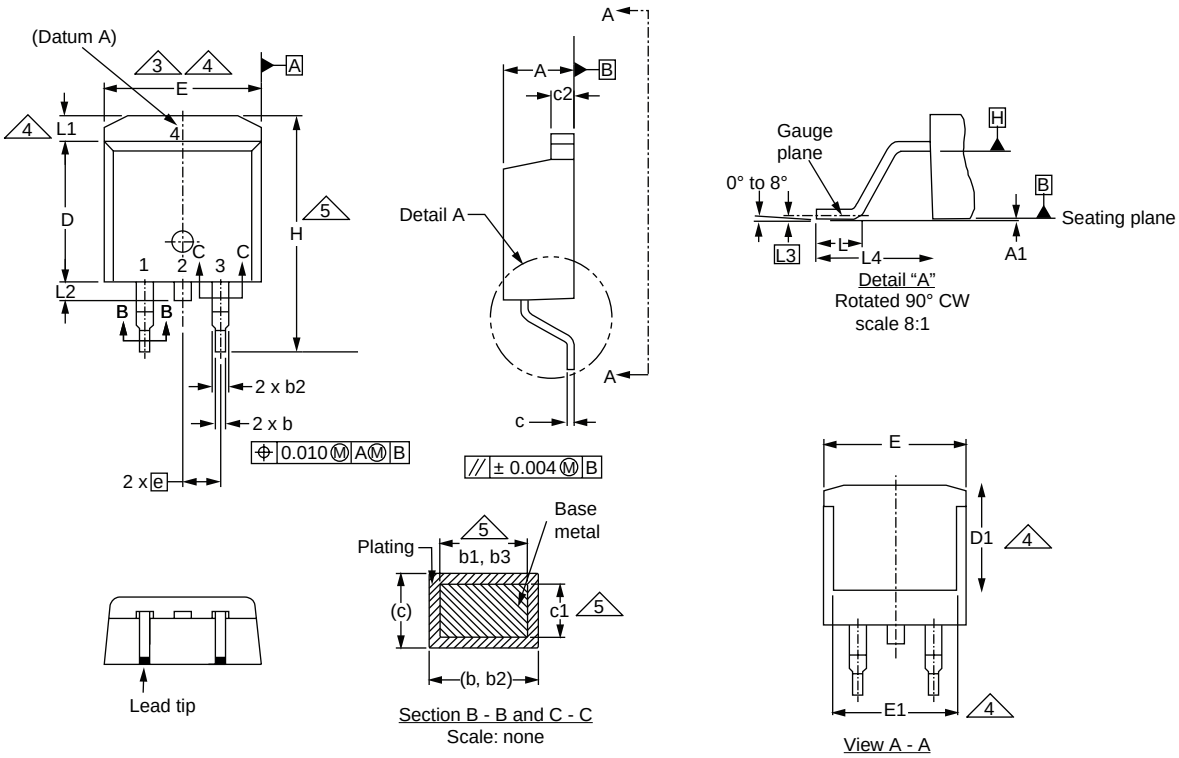


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

TO-263AB



	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

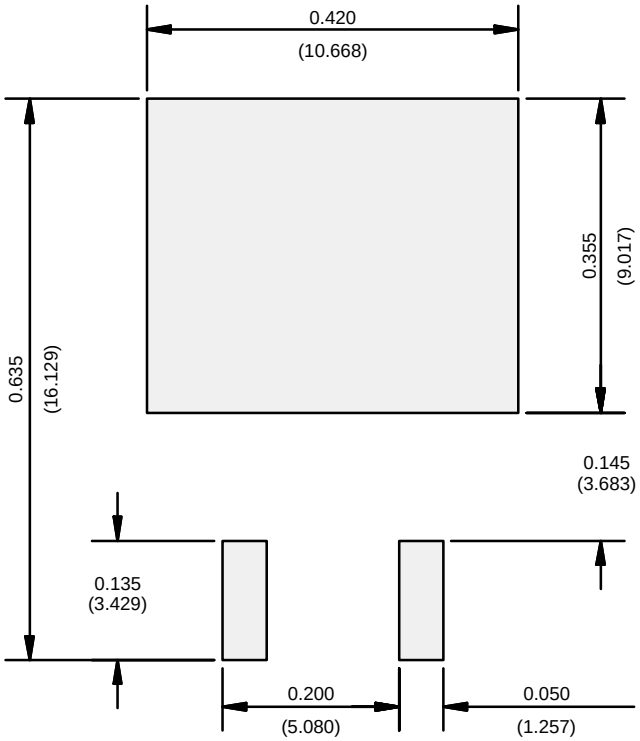
	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	-	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010 BSC	
L4	4.78	5.28	0.188	0.208

ECN: S-82110-Rev. A, 15-Sep-08
DWG: 5970

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.

RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

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